

**A Listing of the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the present application.

**Claim 1 (previously presented):** A holder for use in semiconductor or liquid-crystal manufacturing devices, comprising:

a ceramic susceptor; and

a composite of a ceramic and a metal furnished atop said ceramic susceptor, the composite including a mixture of metallic and ceramic constituents, the mixture including metallic microconstituents distributed in a ceramic matrix.

**Claim 2 (original):** A holder as set forth in claim 1, wherein the Young's modulus of the ceramic-and-metal composite is 300 GPa or less.

**Claim 3 (original):** A holder as set forth in claim 1, wherein the thermal conductivity of the ceramic-and-metal composite is 100 W/mK or more.

**Claim 4 (original):** A holder as set forth in claim 1, wherein the thermal expansion coefficient of the ceramic-and-metal composite is Claim  $2.5 \times 10^{-6}$  to Claim  $8.0 \times 10^{-6}/^{\circ}\text{C}$ .

**Claim 5 (original):** A holder as set forth in claim 1, further comprising a support part supporting the ceramic-and-metal composite.

**Claim 6 (original):** A holder as set forth in claim 1, further comprising a support part supporting the ceramic susceptor.

**Claim 7 (original):** A holder as set forth in claim 1, further comprising a support part supporting both the ceramic-and-metal composite and the ceramic susceptor.

**Claim 8 (original):** A holder as set forth in claim 1, wherein a coating is formed on at least a processed-object-retaining side of the holder.

**Claim 9 (original):** A holder as set forth in claim 1, wherein the ceramic-and-metal composite functions as an electrode.

**Claim 10 (original):** A semiconductor or liquid-crystal manufacturing device in which the holder of claim 1 is installed.

**Claim 11 (previously presented):** A holder for use in semiconductor or liquid crystal manufacturing devices, the holder comprising:

a processing surface configured to hold the semiconductor or liquid crystal manufacturing device;

a ceramic susceptor; and

a ceramic-metal composite deployed between the processing surface and the ceramic susceptor, the ceramic-metal composite including a substantially uniform mixture of ceramic and metal microconstituents.

**Claim 12 (previously presented):** A holder as set forth in claim 11, wherein the processing surface is a surface of the ceramic-metal composite.

**Claim 13 (previously presented):** A holder as set forth in claim 11, wherein the ceramic susceptor comprises a resistive element deployed in or on a surface of a ceramic substrate.

**Claim 14 (previously presented):** A holder as set forth in claim 11, wherein the ceramic-metal composite comprises a sintered mixture of metal and ceramic powders.

**Claim 15 (previously presented):** A holder as set forth in claim 11, wherein the ceramic-metal composite comprises metal infiltrated into a porous ceramic substrate.

**Claim 16 (previously presented):** A holder as set forth in claim 11, wherein: the metal comprises at least one member of the group consisting of Al, Si, and Cu; and

the ceramic comprises at least one member of the group consisting of SiC, Al<sub>2</sub>O<sub>3</sub>, AlN, WC, and BN.

**Claim 17 (previously presented):** A holder as set forth in claim 11, wherein the ceramic-metal composite comprises at least one compound selected from the group consisting of Al—SiC, Al—Al<sub>2</sub>O<sub>3</sub>, Al—AlN, Si—SiC, Si—Al<sub>2</sub>O<sub>3</sub>, and Si—AlN.

**Claim 18 (previously presented):** A holder as set forth in claim 1, wherein the composite comprises a sintered mixture of metal and ceramic powders.

**Claim 19 (previously presented):** A holder as set forth in claim 1, wherein the composite comprises metal infiltrated into a porous ceramic substrate.